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PATENT

In re Application of:

Mu, et al.

Serial No.: 09/661,899

Filed: September 14, 2000

For: PROCESS FOR FORMING A

DIRECT BUILD-UP LAYER ON AN **ENCAPSULATED DIE PACKAGES**

UTILIZING INTERMEDIATE STRUCTURES (As Amended)

Examiner: A. Chambliss

Group Art Unit: 2814

Attorney Docket No.: 42390.P9557 CERTIFICATE OF MAILING

MATCH & RETURN

PRELIMINARY AMENDMENT

Hon. Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

Prior to the examination of the claims on the merits, Applicants respectfully request that the Examiner enter the following amendments:

IN THE SPECIFICATION:

Please delete the title on the cover page and replace with:

PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN

ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE STRUCTURES

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Dated: January 23, 2002

Robert G. Winkle Attorney for Applicants

Reg. No. 37,474